

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2992829

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	YUTAKA INOUE	08/04/2014
	HIDEKI HARA	08/04/2014
	SHUICHI USUDA	08/04/2014
RECEIVING PARTY DATA		
Name:	OCLARO JAPAN INC	
Street Address:	4-1-55 OYAMA, CHUO-KU, SAGAMIHARA	
City:	KANAGAWA	
State/Country:	JAPAN	
Postal Code:	252-5250	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14466039	
CORRESPONDENCE DATA		
Fax Number:	(703)684-1157	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	703-684-1120	
Email:	ptomail@mmiplaw.com, dcashion@mmiplaw.com	
Correspondent Name:	MATTINGLY & MALUR, PC	
Address Line 1:	1800 DIAGONAL ROAD	
Address Line 2:	SUITE 370	
Address Line 4:	ALEXANDRIA, VIRGINIA 22314	
ATTORNEY DOCKET NUMBER:	HPTA-9380	
NAME OF SUBMITTER:	SHRINATH MALUR	
SIGNATURE:	/Shrinath Malur/	
DATE SIGNED:	08/22/2014	
Total Attachments: 1		
source=9380-Assign#page1.tif		

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Oclaro Japan, Inc.
a corporation organized under the laws of Japan,
located at 4-1-55 Oyama, Chuo-ku, Sagami-hara, Kanagawa, 252-5250 Japan
receipt of which is hereby acknowledged I do hereby sell and assign to said Oclaro Japan, Inc.
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MULTI-BEAM SEMICONDUCTOR LASER DEVICE

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Oclaro Japan, Inc.
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Oclaro Japan, Inc.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Yutaka Inoue</u> Yutaka INOUE	<u>4. Aug, 2014</u>
2) <u>Hideki Hara</u> Hideki HARA	<u>4. Aug, 2014</u>
3) <u>Shuichi Usuda</u> Shuichi USUDA	<u>4. Aug, 2014</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____